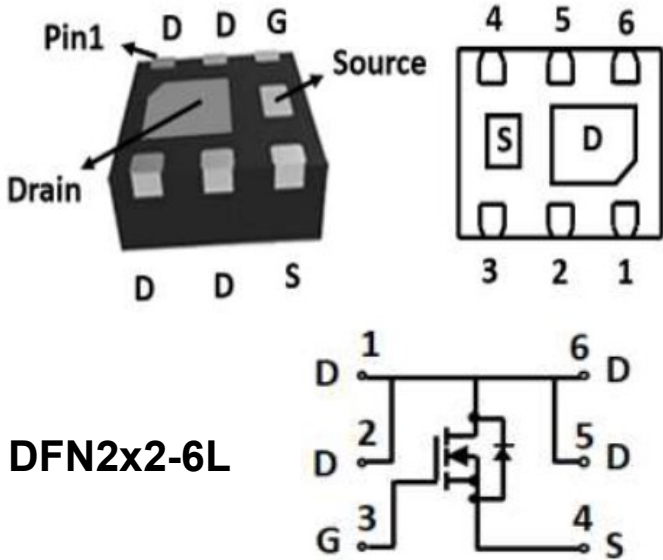


N-Channel Enhancement Mode Field Effect Transistor



DFN2x2-6L

Product Summary

- V_{DS} 20V
- I_D 13A
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) < 9mohm
- $R_{DS(ON)}$ (at $V_{GS}=2.5V$) < 12mohm
- $R_{DS(ON)}$ (at $V_{GS}=1.8V$) < 18.5mohm
- 100% ∇V_{DS} Tested

General Description

- Trench Power LV MOSFET technology
- High density cell design for Low $R_{DS(ON)}$
- High Speed switching

Applications

- Battery protection
- Load switch
- Power management

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

| Parameter | | Symbol | Limit | Unit |
|---|------------------|-----------------|----------|--------------|
| Drain-source Voltage | | V_{DS} | 20 | V |
| Gate-source Voltage | | V_{GS} | ± 10 | V |
| Drain Current | $T_A=25^\circ C$ | I_D | 13 | A |
| | $T_A=70^\circ C$ | | 8 | |
| Pulsed Drain Current ^A | | I_{DM} | 32 | A |
| Total Power Dissipation | $T_A=25^\circ C$ | P_D | 2.2 | W |
| | $T_A=70^\circ C$ | | 1.4 | |
| Thermal Resistance Junction-to-Ambient ^B | | $R_{\theta JA}$ | 57 | $^\circ C/W$ |
| Junction and Storage Temperature Range | | T_J, T_{STG} | -55~+150 | $^\circ C$ |

■ Ordering Information (Example)

| PREFERRED P/N | PACKING CODE | Marking | MINIMUM PACKAGE(pcs) | INNER BOX QUANTITY(pcs) | OUTER CARTON QUANTITY(pcs) | DELIVERY MODE |
|---------------|--------------|---------|----------------------|-------------------------|----------------------------|---------------|
| YJQ10N02A | F1 | Q10N02 | 3000 | 30000 | 120000 | 7" reel |



YJQ10N02A

■ Electrical Characteristics (T_J=25°C unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
|-----------------------------------|---------------------|---|------|-------|------|-------|
| Static Parameter | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V, I _D =250μA | 20 | | | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =20V, V _{GS} =0V | | | 1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±10V, V _{DS} =0V | | | ±100 | nA |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =250μA | 0.45 | 0.62 | 1.0 | V |
| Static Drain-Source On-Resistance | R _{DS(on)} | V _{GS} =4.5V, I _D =13A | | 7.8 | 9 | mΩ |
| | | V _{GS} =2.5V, I _D =6.5A | | 9.5 | 12 | |
| | | V _{GS} =1.8V, I _D =4A | | 12 | 18.5 | |
| Diode Forward Voltage | V _{SD} | I _S =13A, V _{GS} =0V | | | 1.2 | V |
| Dynamic Parameters | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} =10V, V _{GS} =0V, f=1MHZ | | 888 | | pF |
| Output Capacitance | C _{oss} | | | 133 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 117 | | |
| Switching Parameters | | | | | | |
| Total Gate Charge | Q _g | V _{GS} =4.5V, V _{DS} =10V, I _D =6.8A | | 11.05 | | nC |
| Gate-Source Charge | Q _{gs} | | | 1.73 | | |
| Gate-Drain Charge | Q _{gd} | | | 3.1 | | |
| Turn-on Delay Time | t _{D(on)} | V _{GS} =4.5V, V _{DS} =10V, I _D =6.8A R _{GEN} =3Ω | | 7 | | ns |
| Turn-on Rise Time | t _r | | | 46 | | |
| Turn-off Delay Time | t _{D(off)} | | | 30 | | |
| Turn-off fall Time | t _f | | | 52 | | |

A. Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

B. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design, while R_{θJA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.



■ Typical Performance Characteristics

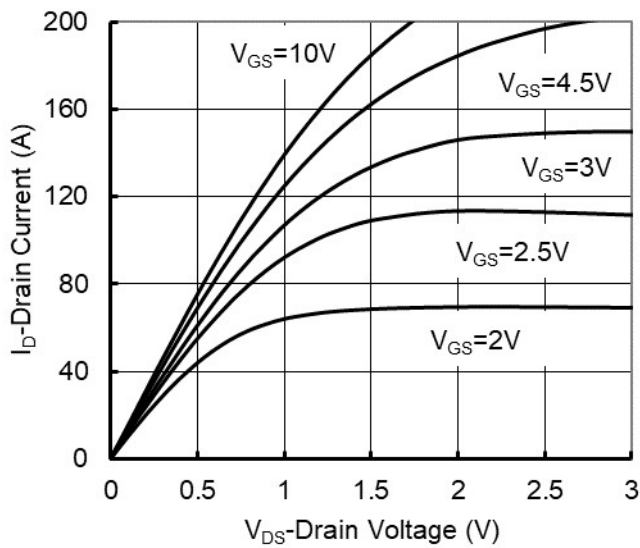


Figure1. Output Characteristics

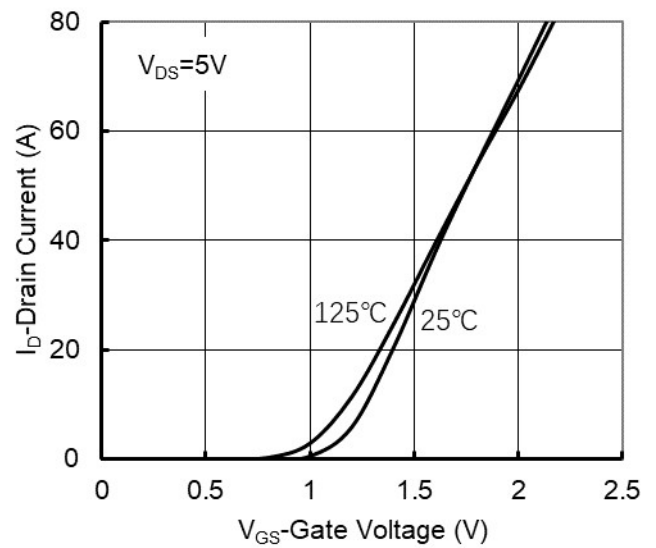


Figure2. Transfer Characteristics

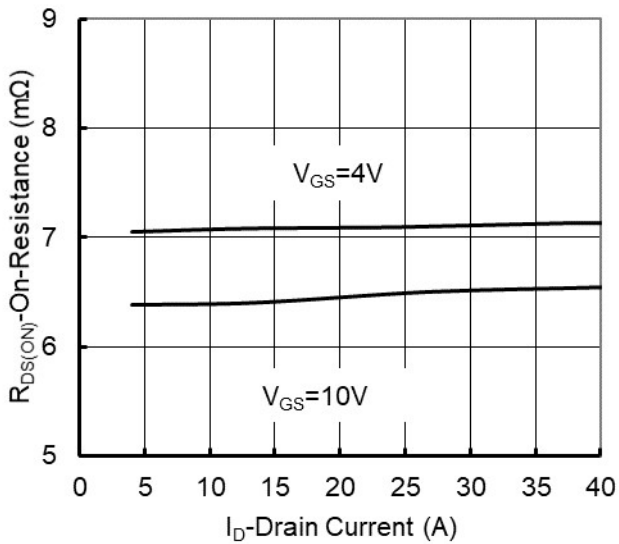


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

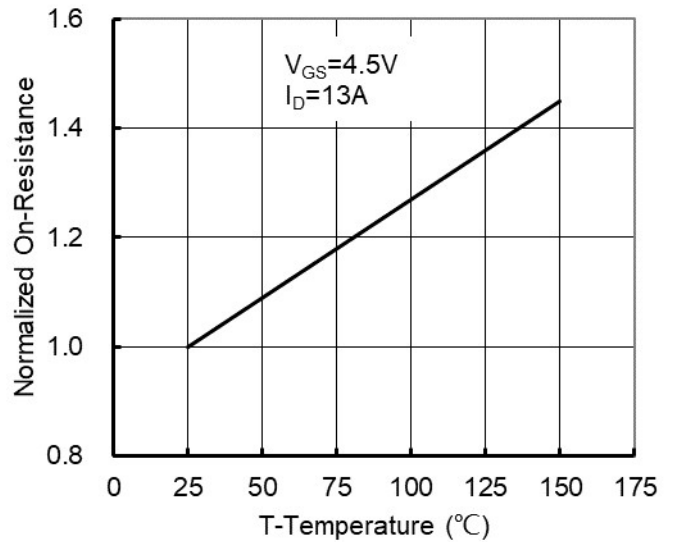


Figure 4: On-Resistance vs. Junction Temperature

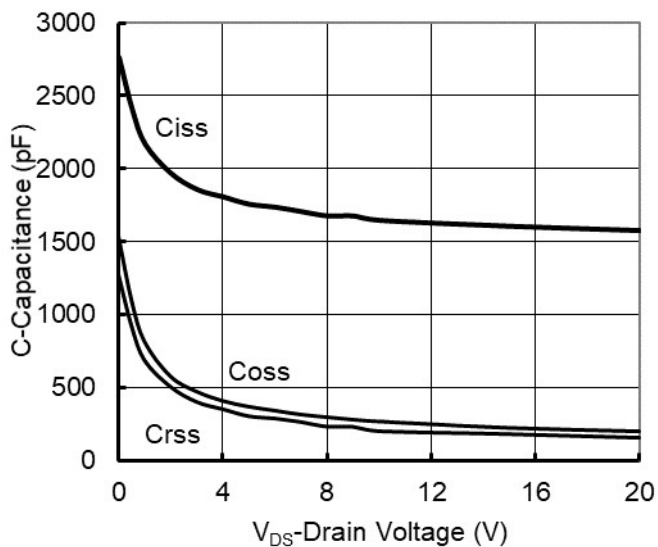


Figure5. Capacitance Characteristics

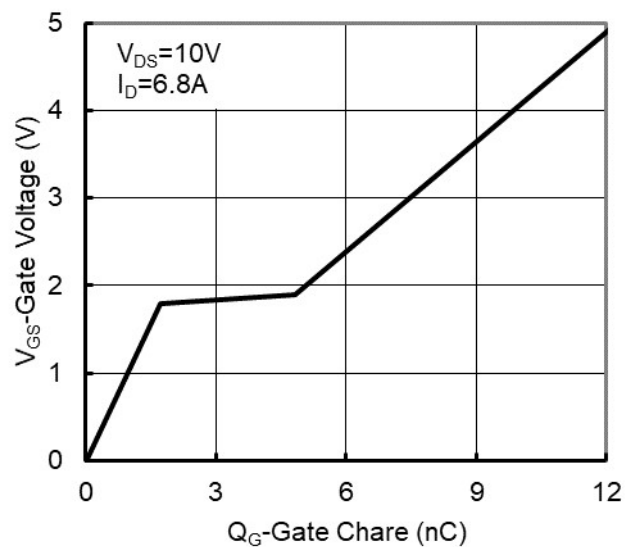


Figure6. Gate Charge



YJQ10N02A

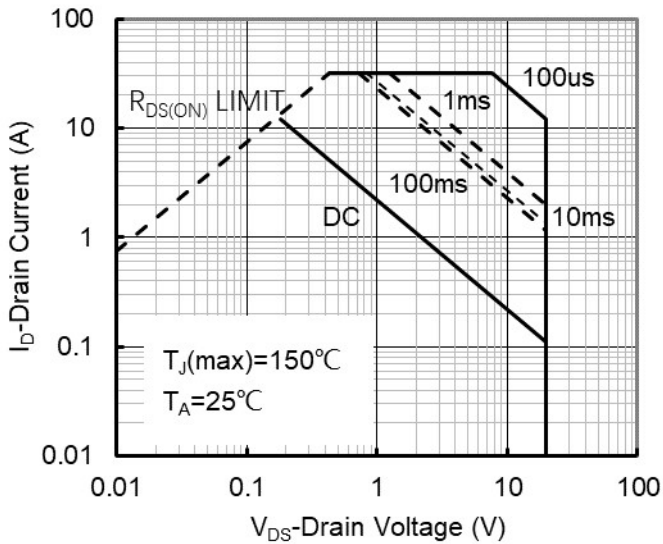


Figure7. Safe Operation Area

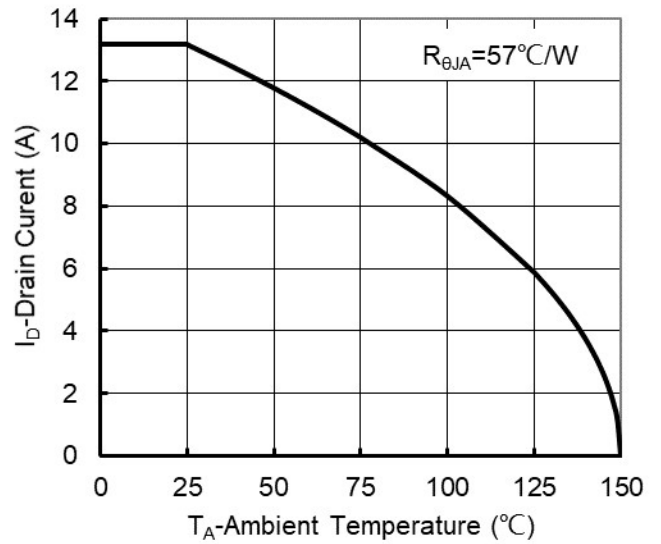


Figure8. Maximum Continuous Drain Current vs Ambient Temperature

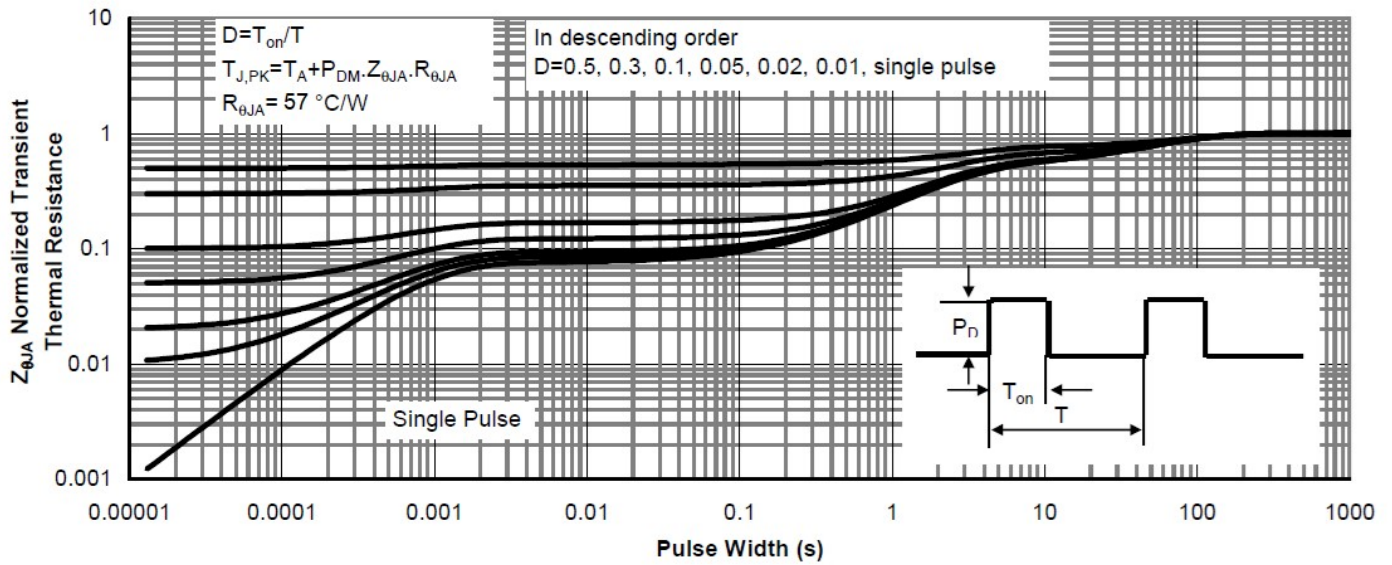
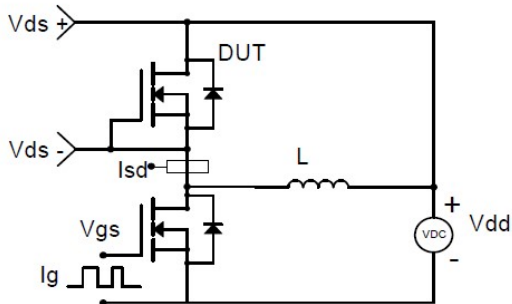


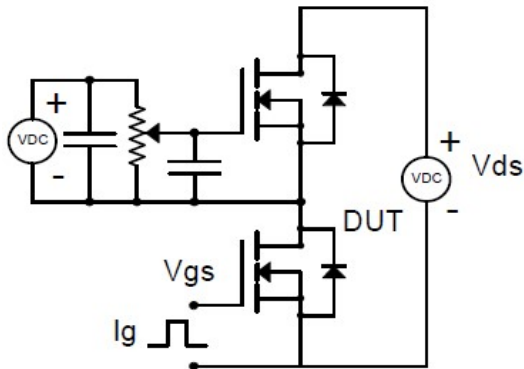
Figure9. Normalized Maximum Transient Thermal Impedance



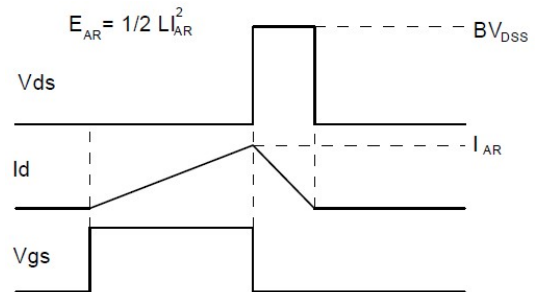
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Gate Charge Test Circuit & Waveform

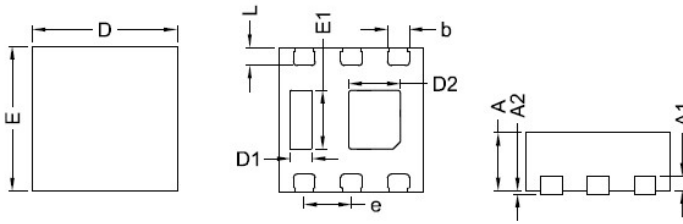


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



YJQ10N02A

■ DFN2x2-6L Package information

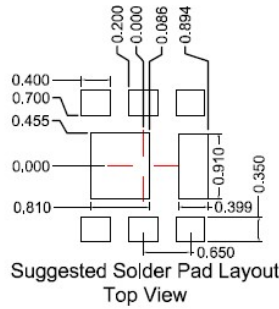


Top View
正面视图

Bottom View
背面视图

Side View
侧面视图

| SYMBOL | MILLIMETER | | |
|--------|------------|------|------|
| | MIN | NOM | MAX |
| D | 1.90 | 2.00 | 2.10 |
| E | 1.90 | 2.00 | 2.10 |
| A | 0.70 | 0.80 | 0.90 |
| A1 | 0.20 BSC | | |
| A2 | | | 0.10 |
| D1 | 0.20 | 0.30 | 0.40 |
| D2 | 0.61 | 0.71 | 0.81 |
| E1 | 0.71 | 0.81 | 0.91 |
| L | 0.15 | 0.25 | 0.35 |
| b | 0.20 | 0.30 | 0.40 |
| e | 0.65 BSC | | |



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.10\text{mm}$.
 3. The pad layout is for reference purposes only.



YJQ10N02A

Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website [http:// www.21yangjie.com](http://www.21yangjie.com) , or consult your nearest Yangjie's sales office for further assistance.